

CLAIMS

1. A multilayer printed circuit board including a substrate having an inner-layer conductor circuit and one or more outer-layer conductor circuits formed on the substrate with an insulating layer laid between the substrate and outer-layer conductor circuit, wherein:

a strain gauge having a resistive element held tight between resin films formed from polyimide or thermoplastic resin is buried in the substrate; and

electrodes electrically connected to the resistive element are exposed to outside from the resin film and are electrically connected at exposed portions thereof to a viahole.

2. The multilayer printed circuit board according to claim 1, wherein the resin films are formed from at least one selected from polyimide or thermoplastic resins such as polyester, polytetrafluoroethylene, etc.

3. The multilayer printed circuit board according to claim 1 or 2, wherein the viahole is filled with a conductive material.

4. The multilayer printed circuit board according to any one of claims 1 to 3, having a plurality of solder bumps or balls formed on the outermost layer thereof.

5. A testing piece for the printed circuit board including a substrate having an inner-layer conductor circuit and one or more outer-layer conductor circuits

formed on the substrate with an insulating layer laid between the substrate and outer-layer conductor circuit, wherein:

a strain gauge having a resistive element held tight between resin films formed from polyimide or thermoplastic resin is buried in the substrate; and electrodes electrically connected to the resistive element are exposed to outside from the resin film and are electrically connected at exposed portions thereof to a viahole.

6. The testing piece for the printed circuit board according to claim 5, wherein the resin films are formed from at least one selected from polyimide or thermoplastic resins such as polyester, polytetrafluoroethylene, etc.

7. The printed circuit board according to claim 5 or 6, wherein the viahole is filled with a conductive material.

8. The multilayer printed circuit board according to any one of claims 5 to 7, having a plurality of solder bumps or balls formed on the outermost layer thereof.